WHAT IS CLAIMED IS:

1. A dressing board, the dressing board comprising:

a substrate not containing abrasive grains; and

a dressing member provided on the substrate and containing abrasive grains;

the dressing board being adapted to be cut by a cutting blade when the substrate and the dressing member comes into contact with the cutting blade in dressing the cutting blade, thereby wearing the cutting blade, wherein

the cutting blade is configured to cut a workpiece;

the substrate is formed of the same material as that of the workpiece; and

the substrate is a separate member from the workpiece and the workpiece is not a part of the dressing board.

2. The dressing board according to claim 1, wherein the substrate has a thickness which is set to a value greater than or equal to the thickness of the dressing member.

3. The dressing board according to claim 1, wherein the thickness of the substrate is in a range of

0.2 to 1 mm, and

the thickness of the dressing member is in a range of 0.05 to 1 mm.

4. The dressing board according to claim 1, wherein when the cutting blade being rotated is made to cut the dressing board, the dressing member is fully cut in its thickness by the cutting blade, while the substrate is partially cut in its thickness.

5. A dressing method of dressing a cutting blade for cutting a workpiece, by using a dressing board, the dressing board comprising a substrate not containing abrasive grains and a dressing member provided on the substrate and containing abrasive grains, the dressing method comprising:

a holding step of holding the substrate side of the dressing board on a chuck table included in a cutting apparatus; and

a dressing step of making the cutting blade cut the dressing member side of the dressing board after performing the holding step, thereby cutting both the dressing member and the substrate by using the cutting blade; wherein

the substrate is formed of the same material as that of the workpiece; and wherein the substrate is a

separate member from the workpiece and the workpiece is not a part of the dressing board.

6. The dressing method according to claim 5, wherein when the cutting blade being rotated is made to cut the dressing board, the dressing member is fully cut in its thickness by the cutting blade, while the substrate is partially cut in its thickness.